

ABSTRACT

POLISHING APPARATUS HAVING SURFACE-PROPERTY MEASURING DEVICE OF POLISHING PAD AND POLISHING SYSTEM

5 The present invention relates to a polishing apparatus having a surface-property
measuring device for measuring surface properties of a polishing pad which is used to polish
a substrate, such as semiconductor wafer, and a polishing system including such a polishing
apparatus. The polishing apparatus includes a surface-property measuring device (30) for
measuring surface properties of a polishing pad (2), a support arm (50) for supporting the
10 surface-property measuring device (30), and a moving unit (53) coupled to the support arm
(50) and configured to move the surface-property measuring device (30) from a retreat
position to a measure position.

Figure 9